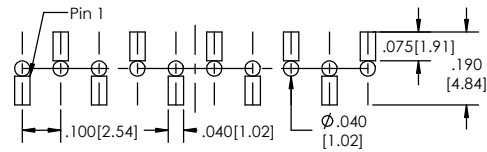
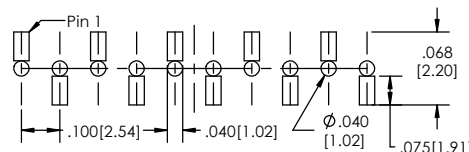


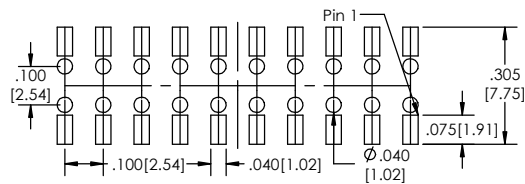
Recommended P.C. Board Layout SCALE 4:1



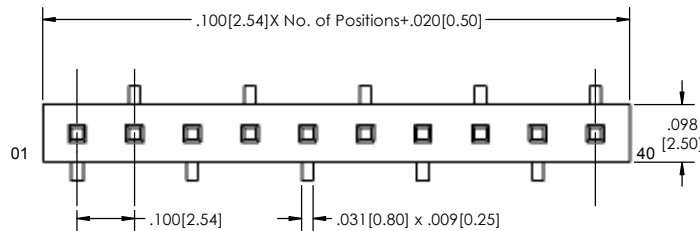
SINGLE (S) ROW



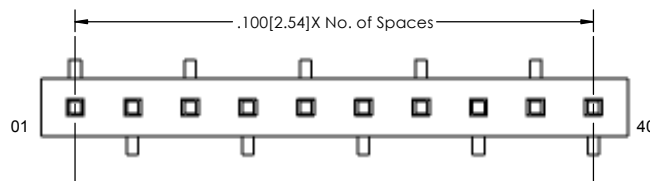
SINGLE (M) ROW



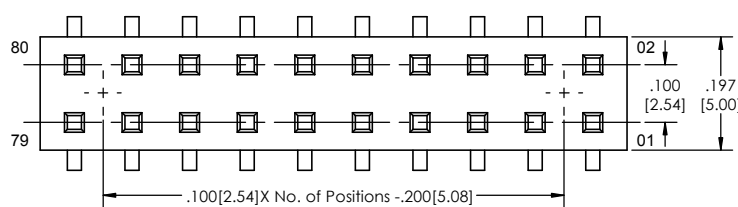
DOUBLE ROW



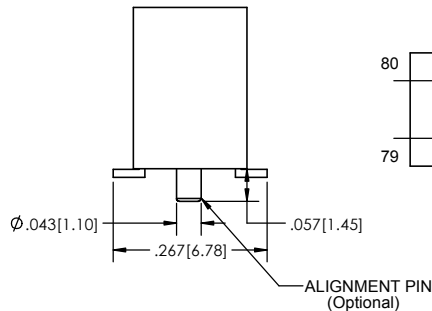
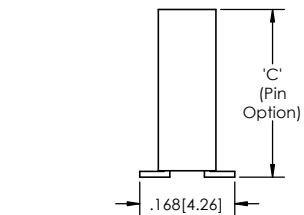
SINGLE (S) ROW



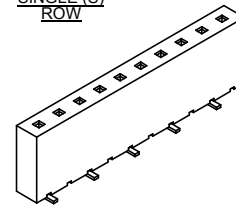
SINGLE (M) ROW



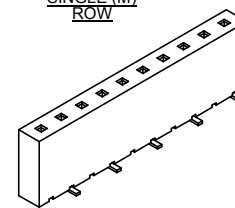
DOUBLE ROW



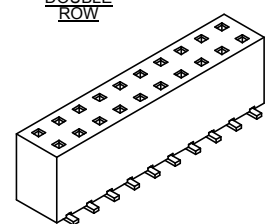
SINGLE (S)
ROW



SINGLE (M)
ROW



DOUBLE
ROW

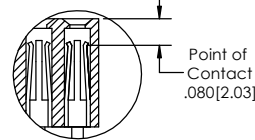
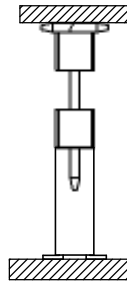


SMBC-1 **XX** - **X** - **XX** - **XX** - **V** - **XXX** - **X** - **XX** - **X** - **XX** - **LF**
(A) (B) (C) (D) (E) (F) (G) (H) (I) (J) (K)

- A. Pins Per Row - 2 through 40
- B. Row Specification - S= Single Row - D= Double Row
- C. Pin Option - .01= .197[5.00] Body Height - .02= .295[7.49] Body Height
- D. Plating Options - See Plating Options below
- E. Direction - V= Vertical
- F. Polarized Position - Leave blank if not needed - If required, specify empty pin position - e.g. 012 for Pin 12
- G. Footprint - S= pin 1 to the right - M= pin 1 to the left
- H. Packing Information - TB= Tube - TR= Tape and Reel - If left blank, packaging at MLE's discretion - Pad may be metal, mylar or plastic
- I. Pad - P= Plastic - K= Kapton - O= No Pad
- J. Alignment Pin (option only available for Double) - Leave blank if not needed - AP= With
- K. Lead Free

Mates With:
BSTC TSHCR
BSTCM TSHCRE
BSTCR TSHCRSM
BSTCRSM TSHR
BSTS TSHRE
LBSTCM TSHS
LTSHCR TSHSCM
LTSHCRE TSHSM
LTSHR ULTSHSM
LTSHRE ULTSHS
LTSHSM ULTHSC
TSHC ULTSHCR

APPLICATION



Plating options	
G	-10µ Gold on Contact Area/ Flash on Tail
T	-Matte Tin all Over
GT	-10µ Gold on Contact Area/ Matte Tin on Tail
H	-30µ Gold on Contact Area/ Matte Tin on Tail
F	-Gold Flash over Entire Pin
FT	- Gold Flash on Contact Area/ Matte Tin on Tail

Specifications:
Insertion Depth: .145[3.68] to .250[6.35]
Insertion Force- Per Contact- H Plating:
5oz. [1.39N] avg with .025[0.64mm] sq. pin
Withdrawal Force- Per Contact- H Plating:
3oz. [0.83N] avg with .025[0.64mm] sq. pin
Current Rating: 3.0 Ampere
Insulation Resistance: 1000M Ohms Min.
Dielectric Withstanding: 600V AC
Contact Resistance: 20M Ohms Max.
Operation Temperature: -40°C to +105°C
Max. Process Temperature
Peak: 260°C up to 20 secs.
Process: 230°C up to 60 secs.
Wave: 260°C up to 6 secs.
Reflow: 260°C up to 10 secs.
Manual Solder: 350°C up to 5 secs.

Materials:
Contact Material: Phosphor Bronze
Insulator Material: Nylon 6T
Plating: Au or Sn over 50µ" (1.27) Ni
Tails may be clipped to achieve specific dimensions.

Products cut to specific sizes are uncancellable/ nonreturnable.
Parts are subject to change without notice.



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UNLESS OTHERWISE SPECIFIED:		NAME	DATE
DIMENSIONS ARE IN INCHES		EOW	10/14/15
TOLERANCES:		CHECKED	GWE
ONE DECIMALS ±.100		ENG APPR.	
TWO DECIMAL ±.010		MFG APPR.	
THREE DECIMAL ±.005		ADDRESS:	
FOUR DECIMAL ±.002		2533 Centennial Blvd.	
NEXT ASSY USED ON		Jeffersonville, IN 47130	
APPLICATION		Phone: 812-670-4174	
DO NOT SCALE DRAWING		Fax: 812-670-4175	
		E-Mail: mle@mlerlectronics.com	
		TITLE: SMBC-1-V SERIES	
		SIZE DWG. NO.	
		C	
		REV D	
		SCALE 6:1	
		SHEET 1 OF 1	

